

Title (en)

COMPOSITION FOR PRINTING A SEED LAYER AND PROCESS FOR PRODUCING CONDUCTOR TRACKS

Title (de)

ZUSAMMENSETZUNG ZUM DRUCKEN EINER KEIMSCHICHT UND VERFAHREN ZUR HERSTELLUNG VON LEITERBAHNEN

Title (fr)

COMPOSITION POUR L'IMPRESSION D'UNE COUCHE D'ENSEMENCEMENT ET PROCÉDÉ POUR LA PRODUCTION DE PISTES CONDUCTRICES

Publication

**EP 2537401 A1 20121226 (EN)**

Application

**EP 11744336 A 20110211**

Priority

- EP 10153750 A 20100216
- IB 2011050577 W 20110211
- EP 11744336 A 20110211

Abstract (en)

[origin: WO2011101777A1] A composition for printing a seed layer for electrodeposition or electroless deposition of a metal for the production of full-area or structured metallic surfaces on a substrate is provided. The composition comprises 0.1 to 6% by weight of electrolessly and/or electrolytically coatable particles, 40-98.8% by weight of at least one solvent, 0 to 15% by weight of a crosslinker, 0.1 to 6% by weight of at least one dispersing additive, 0 to 5% by weight of at least one further additive and 1 to 20% by weight of at least one polymer, said at least one polymer being in the form of a dispersion. A process for producing full-area or structured metallic surfaces on a substrate is provided. A use of the process is also provided.

IPC 8 full level

**H05K 3/38** (2006.01); **H01B 1/24** (2006.01); **H05K 1/09** (2006.01); **H05K 3/12** (2006.01)

CPC (source: EP KR)

**H01B 1/22** (2013.01 - EP KR); **H05K 1/097** (2013.01 - EP KR); **H05K 3/1216** (2013.01 - KR); **H05K 3/1283** (2013.01 - KR);  
**C09J 2433/003** (2013.01 - KR); **C09J 2475/003** (2013.01 - KR); **H05K 3/1216** (2013.01 - EP)

Citation (search report)

See references of WO 2011101777A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**WO 2011101777 A1 20110825**; CN 102771198 A 20121107; CN 102771198 B 20160706; EP 2537401 A1 20121226;  
KR 20120137481 A 20121221

DOCDB simple family (application)

**IB 2011050577 W 20110211**; CN 201180009446 A 20110211; EP 11744336 A 20110211; KR 20127024135 A 20110211